Equipment Information Sheet

High-temperature PDMS Curing Oven (2nd Floor)

Manager: Xinwei Wu 607-254-4934 Backup: Michael Skvarla 607-254-4674 Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

• BURN HAZARD: oven can heat to high temperatures.

USAGE RESTRICTIONS

• Leave your name and contact info on the door of the oven.

SCHEDULING/SIGN-UP RESTRICTIONS

- Do NOT use longer than 3 days at a time.
- This is NOT to be used for storing samples.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

| Allowed | Not Allowed |
|---|--|
| Tool category 1/1E, 2, 3, and 4 materials | |
| Silicon Based Substrates and Films | |
| III/V compound Semiconductors | |
| Glass Substrates | |
| PECVD and ALD Films | |
| Cured organics and baked Photoresist | |
| CNF Class A, B, and Refractory metals | |
| Exposed Gold, Silver, Copper | |
| Alkali and Alkaline Compounds | |
| Organic/Biology Molecules prepared- w/salt buffers | |
| High Vapor Pressure Materials (Mg, Ca, Zn)* | * Some tool restrictions on high vapor pressure materials may apply |
| Soft organic materials | |

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- USE GLASS DISHES ONLY. Never use plastic dishes above 60°C. Plastics will melt.
- Turn the oven OFF when finished.

Last Updated: 01/13/2022

Minimum Tool Time: 0 minutes